

Type number	Package	Package description	Total product weight
74AHC30PW	SOT402-1	TSSOP14	56.17966 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935264187118	10	1	260	30 s	1	240	20 s	3	Nijmegen, Netherlands; Bangkok, Thailand; Suzhou, China	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.51264	80.10000	0.91250
	Polymer	Resin system	Proprietary	0.12736	19.90000	0.22670
		subTotal		0.64000	100.00000	1.13920
Die	Doped silicon	Silicon (Si)	7440-21-3	0.21906	100.00000	0.38993
		subTotal		0.21906	100.00000	0.38993
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	20.46870	97.47000	36.43436
		Iron (Fe)	7439-89-6	0.50400	2.40000	0.89712
		Phosphorous (P)	7723-14-0	0.00630	0.03000	0.01121
		Zinc (Zn)	7440-66-6	0.02100	0.10000	0.03738
		subTotal		21.00000	100.00000	37.38007
Mould Compound	Additive	Non hazardous	Proprietary	1.59330	4.70000	2.83608
	Filler	Silica fused	60676-86-0	26.78100	79.00000	47.67028
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	2.03400	6.00000	3.62053
	Pigment	Carbon black	1333-86-4	0.06780	0.20000	0.12068
	Polymer	1,4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	1.35600	4.00000	2.41368
		Non hazardous	Proprietary	1.38990	4.10000	2.47403
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.67800	2.00000	1.20684
		subTotal		33.90000	100.00000	60.34212
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00350	1.00000	0.00623
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.33950	97.00000	0.60431
		Palladium (Pd)	7440-05-3	0.00700	2.00000	0.01246
		subTotal		0.35000	100.00000	0.62300
Wire	Pure metal	Copper (Cu)	7440-50-8	0.07060	100.00000	0.12566
		subTotal		0.07060	100.00000	0.12566

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